Surface Mount Schottky Barrier Rectifier Reverse Voltage - 60V

Forward Current - 5.0A

FEATURES

- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- · Low power loss, high efficiency
- · High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications
- Hireliability application and automotive grade AEC-Q101 qualified

MECHANICAL DATA

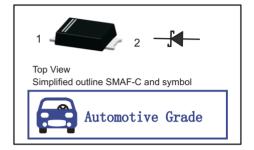
· Case: SMAF-C

• Terminals: Solderable per MIL-STD-750, Method 2026

• Approx. Weight: 27mg / 0.00095oz

PINNING

| PIN | DESCRIPTION | |
|-----|-------------|--|
| 1 | Cathode | |
| 2 | Anode | |



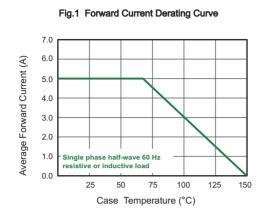
Absolute Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

| Parameter | Symbols | AT-SS56LFCM | Units |
|--|--|-----------------|------------------|
| Maximum Repetitive Peak Reverse Voltage | V_{RRM} | 60 | V |
| Maximum RMS voltage | V _{RMS} | 42 | V |
| Maximum DC Blocking Voltage | V _{DC} | 60 | V |
| Maximum Average Forward Rectified Current @ Fig.1 | I _{F(AV)} | 5.0 | А |
| Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method) | I _{FSM} | 100 | А |
| Peak Forward Surge Current,1.0ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method) | I _{FSM} | 200 | А |
| I ² t Rating for fusing (3ms≤t≤8.3ms) | l²t | 41.5 | A ² S |
| Max Instantaneous Forward Voltage at 5 A | V _F | 0.62 | V |
| Maximum DC Reverse Current $T_a = 25$ °C at Rated DC Reverse Voltage $T_a = 100$ °C | I _R | 0.4 15 | mA |
| Typical Junction Capacitance (1) | Cj | 220 | pF |
| Typical Thermal Resistance (2) | R _{θJA} R _{θJC} R _{θJL} | 100 20 30 | °C/W |
| Operating Junction Temperature Range | Tj | -55 ~ +150 | °C |
| Storage Temperature Range | T _{stg} | -55 ~ +150 | °C |

⁽¹⁾ Measured at 1 MHz and applied reverse voltage of 4 V D.C

⁽²⁾ P.C.B. mounted with 0.2" X 0.2" (5 X 5 mm) copper pad areas.



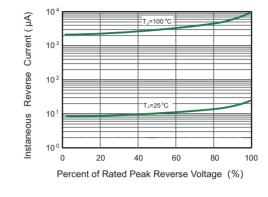


Fig.2 Typical Reverse Characteristics



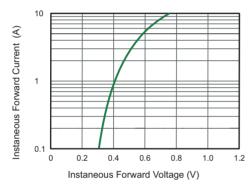


Fig.4 Typical Junction Capacitance

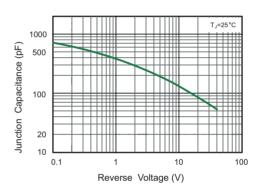
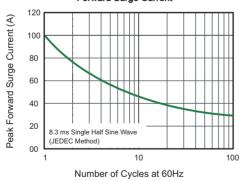


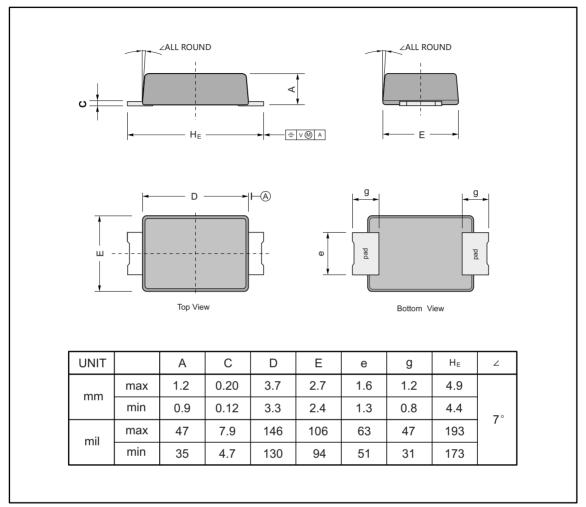
Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



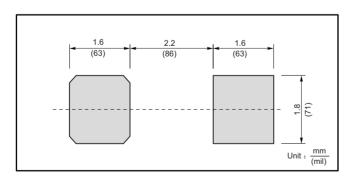
PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SMAF-C



The recommended mounting pad size



Marking

| Type number | Marking code |
|-------------|--------------|
| AT-SS56LFCM | S56L |

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